SAMSUNG ELECTRO-MECHANICS

201312

Chip Bead For EMI Suppression

CIB/CIM10 Series (1608/ EIA 0603)

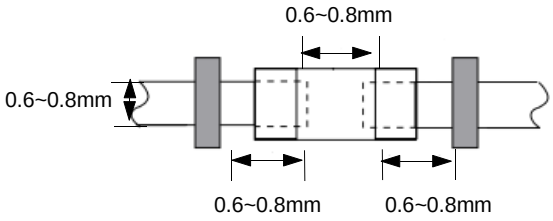
APPLICATION

High frequency EMI prevention application to computers, printers, VCRs, TVs and mobile phones.

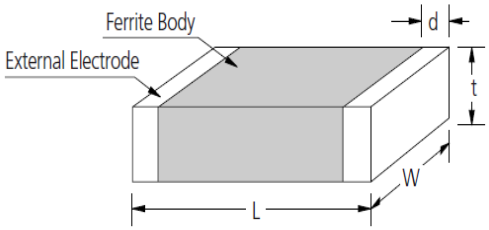
FEATURES

- Perfect shape for automatic mounting, with no directionality.
- Excellent solderability and high heat resistance for either flow or reflow soldering
- Monolithic inorganic material construction for high reliability
- Closed magnetic circuit configuration avoids crosstalk and is suitable for high density PCBs.

RECOMMENDED LAND PATTERN



DIMENSION



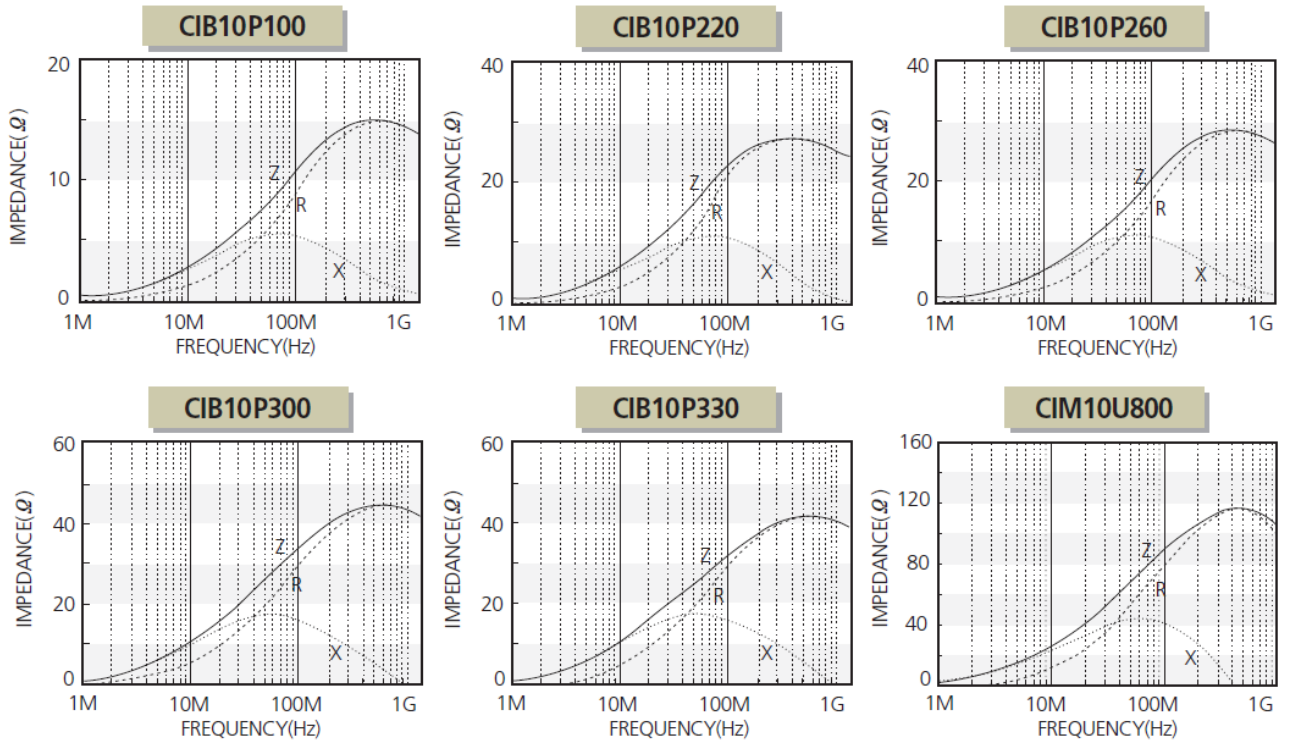
Type	Dimension [mm]			
	L	W	t	d
10	1.6±0.15	0.8±0.15	0.8±0.15	0.3±0.2

DESCRIPTION

Part no.	Thickness (mm)	Impedance (Ω)±25%@100MHz	DC Resistance (Ω) Max.	Rated Current (mA) Max.
CIB10P100	0.8±0.15	10	0.05	1000
CIB10P220	0.8±0.15	22	0.05	1500
CIB10P260	0.8±0.15	26	0.08	1000
CIB10P300	0.8±0.15	30	0.08	1000
CIB10P330	0.8±0.15	33	0.08	1000
CIM10U600	0.8±0.15	60	0.15	600
CIM10U800	0.8±0.15	80	0.10	600
CIM10U121	0.8±0.15	120	0.15	500
CIM10U221	0.8±0.15	220	0.25	400
CIM10U241	0.8±0.15	240	0.25	400
CIM10U301	0.8±0.15	300	0.30	400
CIM10U471	0.8±0.15	470	0.35	300
CIM10U601	0.8±0.15	600	0.38	500
CIM10U102	0.8±0.15	1000	0.50	400
CIM10U202	0.8±0.15	2000(at 70MHz)	1.20	200
CIB10J300	0.8±0.15	30	0.10	1000
CIM10J400	0.8±0.15	40	0.12	600
CIM10J470	0.8±0.15	47	0.12	600
CIM10J600	0.8±0.15	60	0.12	600
CIM10J750	0.8±0.15	75	0.15	550
CIM10J800	0.8±0.15	80	0.15	550
CIM10J121	0.8±0.15	120	0.20	500
CIM10J151	0.8±0.15	150	0.20	400
CIM10J221	0.8±0.15	220	0.30	400
CIM10J241	0.8±0.15	240	0.30	400

Part no.	Thickness (mm)	Impedance (Ω)±25%@100MHz	DC Resistance (Ω) Max.	Rated Current (mA) Max.
CIM10J301	0.8±0.15	300	0.35	400
CIM10J331	0.8±0.15	330	0.35	400
CIM10J471	0.8±0.15	470	0.35	300
CIM10J601	0.8±0.15	600	0.45	300
CIM10J751	0.8±0.15	750	0.50	300
CIM10J102	0.8±0.15	1000	0.60	250
CIM10J152	0.8±0.15	1500	0.70	250
CIM10J252	0.8±0.15	2500	1.50	200
CIM10K152	0.8±0.15	1500	0.80	250
CIM10K202	0.8±0.15	2000	1.00	200
CIM10K252	0.8±0.15	2500	1.20	200
CIM10N700	0.8±0.15	70	0.30	500
CIM10N121	0.8±0.15	120	0.45	400
CIM10N241	0.8±0.15	240	0.60	300
CIM10F470	0.8±0.15	47	0.25	550
CIM10F600	0.8±0.15	60	0.25	550
CIM10F121	0.8±0.15	120	0.30	500
CIM10F331	0.8±0.15	330	0.58	400
CIM10F471	0.8±0.15	470	0.85	300

CHARACTERISTIC DATA



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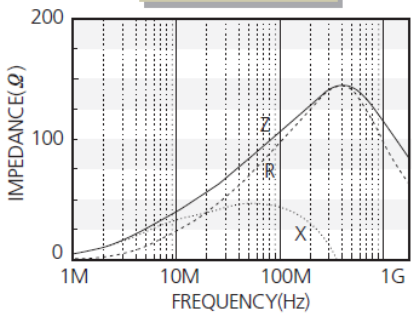

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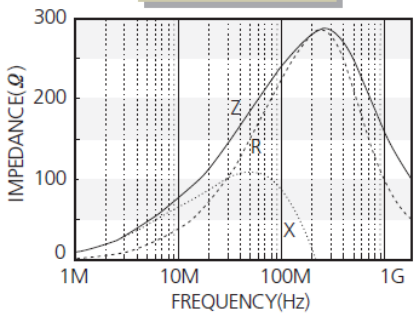

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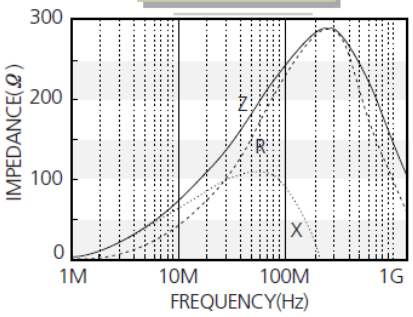

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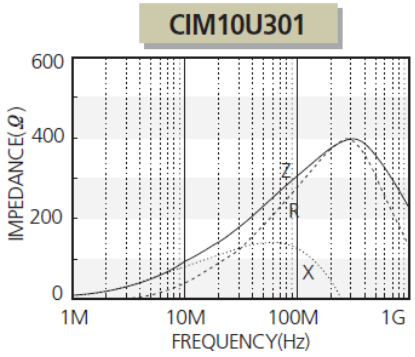

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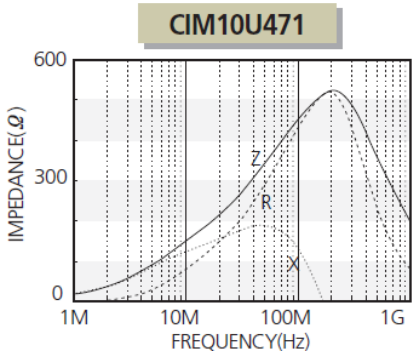

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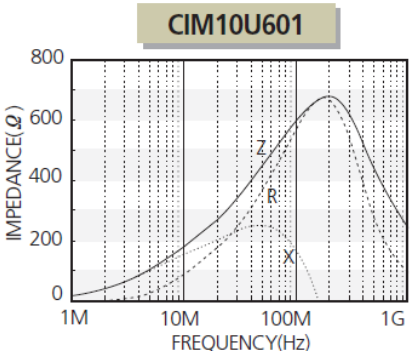

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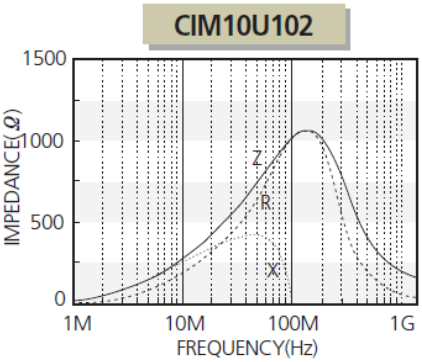

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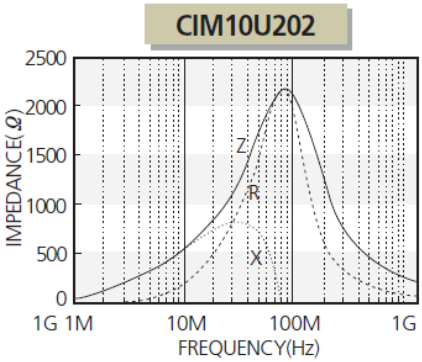

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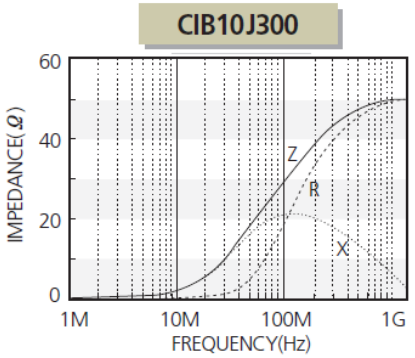

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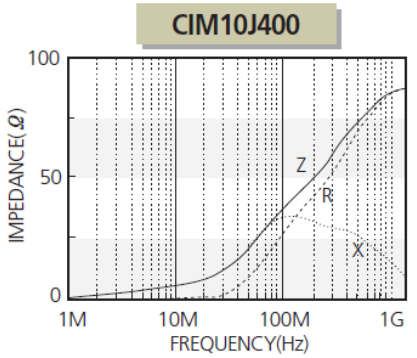

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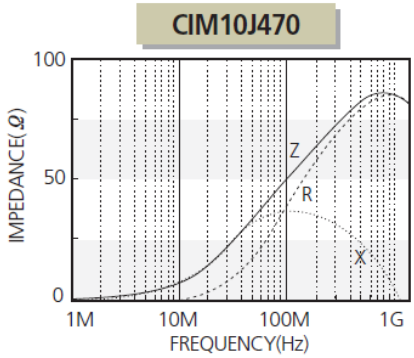

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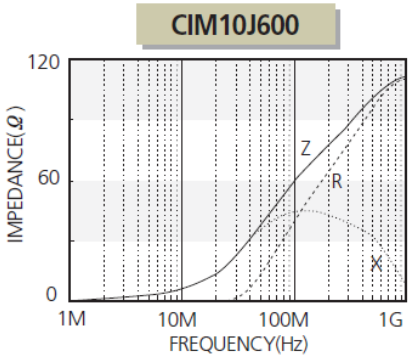

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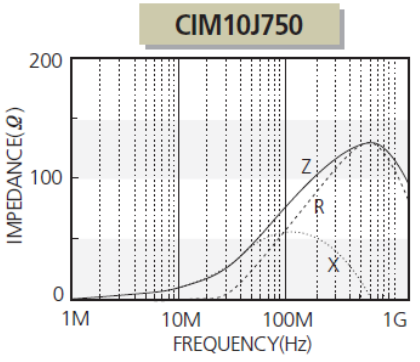

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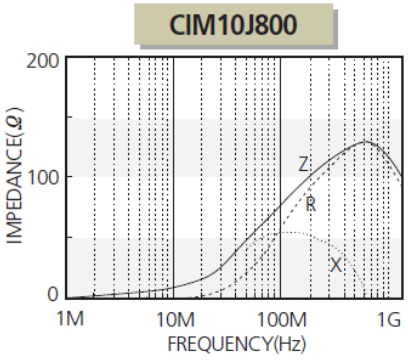

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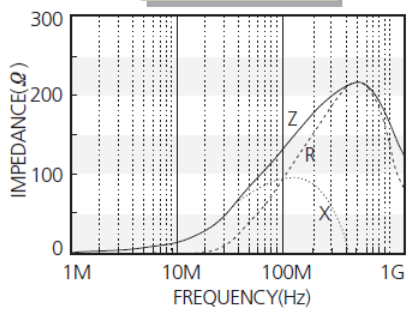

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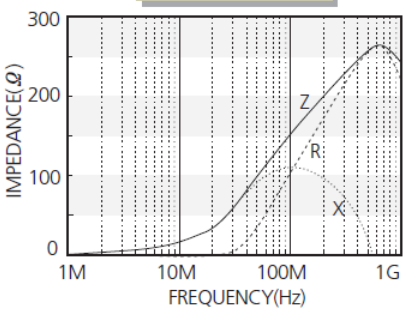

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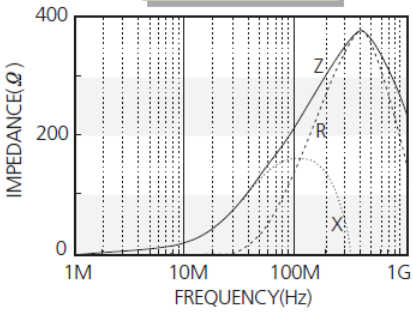

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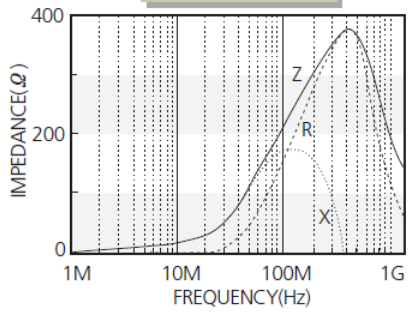

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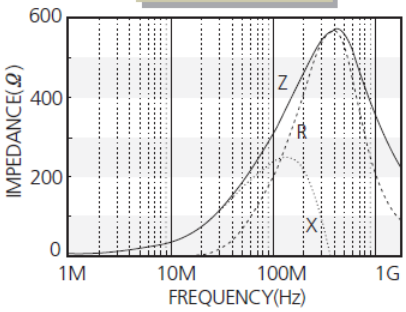

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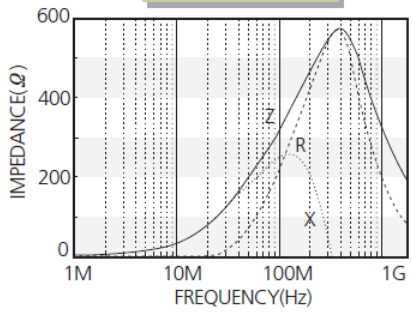

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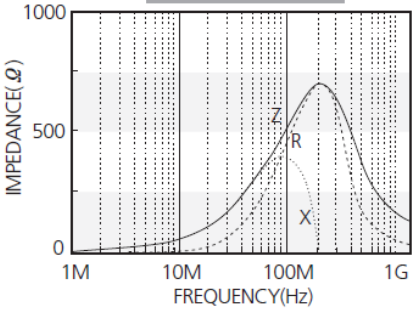

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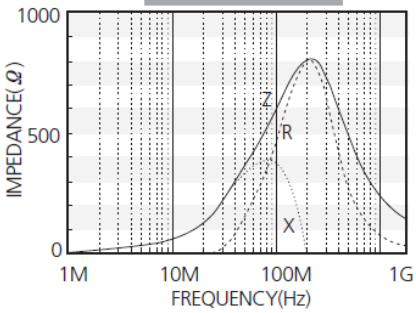

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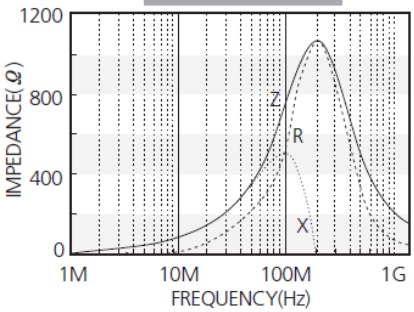

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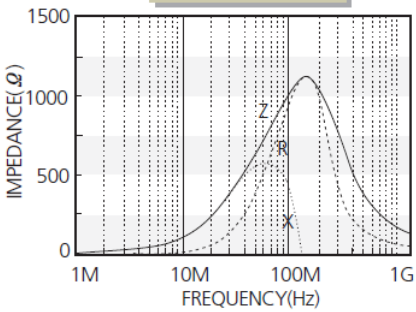

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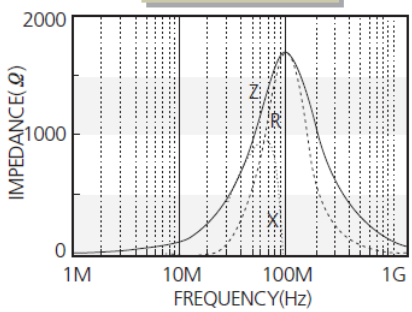

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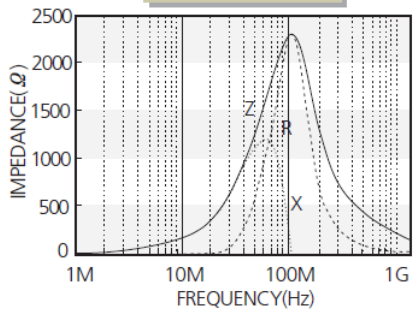

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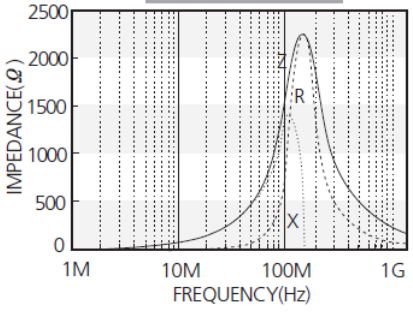

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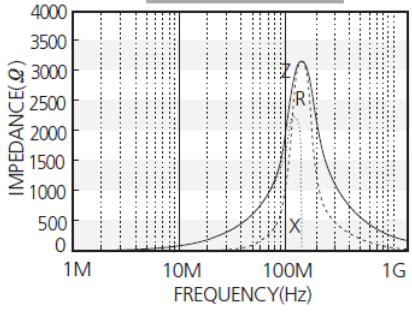

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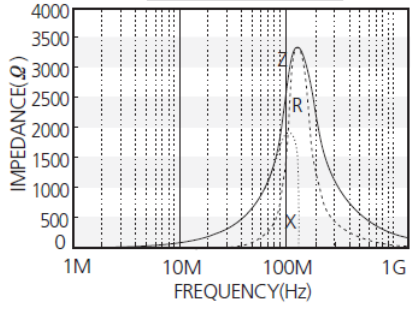
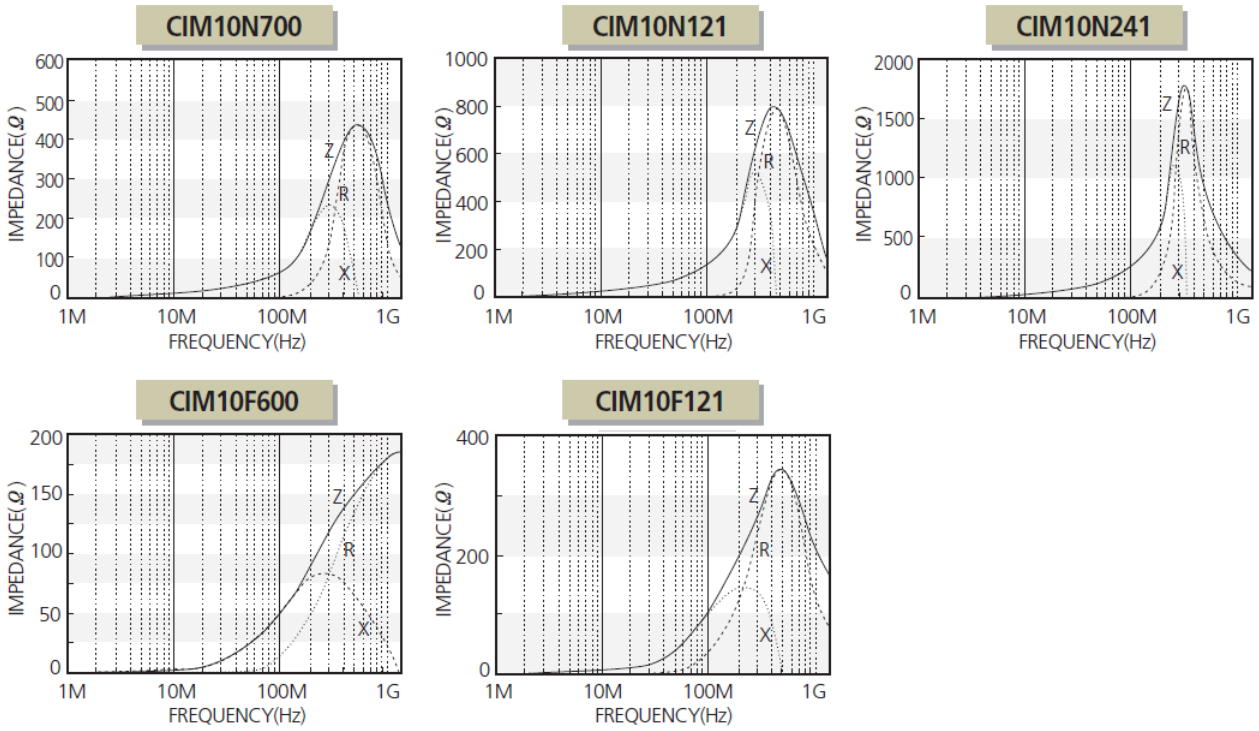




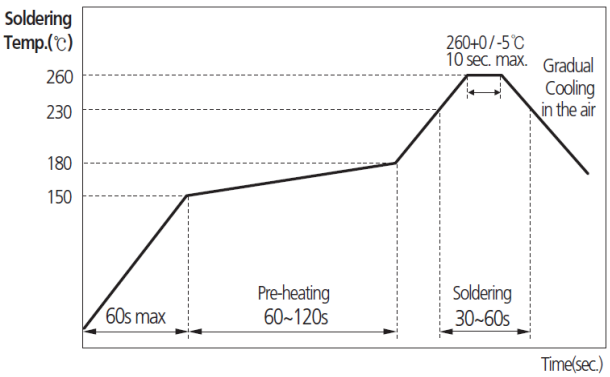
PRODUCT IDENTIFICATION

CI	M	10	U	121	N	C
(1)	(2)	(3)	(4)	(5)	(6)	(7)

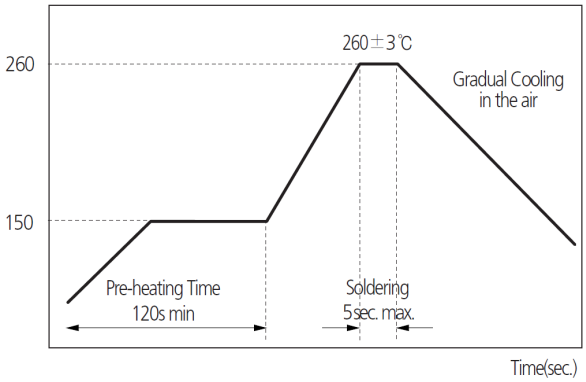
(1) Chip Beads
(2) M: Multi-layer type B:Mono-layer type
(3) Dimension
(4) Material Code
(5) Nominal impedance (121:120Ω, 202:2000Ω)
(6) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
(7) Packaging(C:paper tape(7"), D:Paper tape(13"), E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



PACKAGING

Packaging Style	Quantity(pcs/reel)
Card Board Taping (7")	4,000
Card Board Taping (13")	16,000

Any data in this sheet are subject to change, modify or discontinue without notice.
The data sheets include the typical data for design reference only. If there is any question regarding the data sheets, please contact our sales personnel or application engineers.